



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251022002.1

Qualification of RFAB using qualified Process Technology, Datasheet, Die Revision, additional Assembly site and options for select devices

Change Notification / Sample Request

Date: October 23, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

As referenced in the "reason for change" below, this particular PCN relates to TI's multiyear transition, announced in 2020, to close our 150mm production and move more capacity into 300mm. We are entering the final phases of this transition, and the final 150mm wafers started in October 2025. **Thus, it's critical that you take the appropriate actions, noted in this PCN, to prepare for applicable product changes.**

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20251022002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS79601DCQR	TPS79601DCQR
TPS79501DCQG4	NULL
TPS79501DCQR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251022002.1	PCN Date:	October 23, 2025
Title:	Qualification of RFAB using qualified Process Technology, Datasheet, Die Revision, additional Assembly site and options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	January 21, 2026	Sample requests accepted until:	December 22, 2025*
*Sample requests received after December 22, 2025 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology and additional Assembly site for the devices listed below.

Current Fab Site		Additional Fab Site			
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DFAB	LBC3	200 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1

	Current	Additional
Assembly Site	HNA	TFME
Wire diam/type	Au; 1.5mil	Cu; 1.0mil
Mount compound	SID#400728	SID#A-21
Mold compound	SID#450179	SID#R-32
Passivation layer material	Nitride	Oxide, SiON
Marking Appearance	Laser Dot	Molded Dimple

Group 2

	Current	Additional
Assembly Site	TIEMA	TFME
Lead Finish	Matte Sn	NiPdAu
Wire diam/type	Au; 1.5mil	Cu; 1.0mil
Mount compound	8075531, 4213245	SID#A-21
Mold compound	8096890	SID#R-32
Passivation layer material	Nitride	Oxide, SiON
Marking Appearance	Laser Dot	Molded Dimple

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

Changes from Revision P (January 2015) to Revision Q (June 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed device name to condensed <i>TPS796</i> to consolidate all voltage option devices under one device name.....	1
• Changed entire document to align with current family format.....	1
• Added new silicon (M3) devices to document.....	1
• Added nomenclature distinguishing between new chip and legacy chip information throughout document.....	1
• Changed <i>Features, Applications, and Description</i> sections.....	1
• Changed <i>Pin Configuration and Functions</i> section.....	3
• Added new silicon curves to <i>Typical Characteristics</i> section	8
• Added new chip block diagrams to <i>Functional Block Diagrams</i> section.....	14
• Added <i>Active Discharge (New Chip)</i> section.....	16
• Changed <i>Shutdown</i> section.....	16
• Changed <i>Undervoltage Lockout (UVLO)</i> section.....	16
• Changed <i>Regulator Protection</i> section and added subsections.....	17
• Added steady dropout state discussion in second paragraph to <i>Dropout Operation</i> section.....	19
• Added subsections to <i>Application Information</i>	20
• Changed <i>Design Parameters</i> table.....	25
• Changed <i>Detailed Design Procedure</i> section.....	25
• Changed <i>Application Curves</i> section.....	26
• Changed title from <i>Do's and Don'ts</i> to <i>Best Design Practices</i>	26
• Added <i>Estimating Junction Temperature</i> section.....	26
• Added M3 information to <i>Available Options</i> table.....	31

Changes from Revision J (May 2019) to Revision K (June 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added new silicon (M3) devices to document.....	1
• Added nomenclature distinguishing between new chip and legacy chip information throughout document.....	1
• Added portfolio device bullet to <i>Features</i> section.....	1
• Changed <i>Applications</i> section.....	1
• Changed <i>Description</i> section.....	1
• Changed <i>Pin Configuration and Functions</i> section.....	3
• Added new silicon curves to <i>Typical Characteristics</i> section.....	7
• Changed <i>Overview</i> section.....	14
• Added new chip diagrams to <i>Functional Block Diagrams</i> section.....	14
• Changed <i>Application Information</i> section.....	19
• Changed <i>Input and Output Capacitor Requirements</i> section.....	19
• Changed <i>Output Noise</i> section.....	20
• Changed <i>Application Curves</i> section.....	22
• Changed <i>Layout Examples</i> section.....	26
• Added <i>Device Nomenclature</i> section.....	29

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TPS796	SLVS351P	SLVS351Q	http://www.ti.com/product/TPS796
TPS795	SLVS350J	SLVS350K	http://www.ti.com/product/TPS795

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 200-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

REACH

Green Status

IEC 62474

<input checked="" type="checkbox"/> No Change			
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Changes to product identification resulting from this PCN:

Fab Site

Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DFAB	DLN	USA	Dallas
RFAB	RFB	USA	Richardson

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
A	A

Assembly Site

Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
HNA	HNT	THA	Ayutthaya
TIEMA	GNZ	MYS	MELAKA
TFME	NFM	CHN	Economic Development Zone

Sample product shipping label (not actual product label):



Product Affected – Group 1

TPS79501DCQG4

Product Affected – Group 2

TPS79501DCQ	TPS79501DCQR	TPS79601DCQ	TPS79601DCQR
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Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS79601DCQRM3	Qual Device: TPS79501DCQRM3	Process QBS Reference: TLV62568DBVR	Package QBS Reference: TPS73701QDCQRM3Q1	Package QBS Reference: TPS73733DCQRM3
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/135/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/3000/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-

Type	#	Test Name	Condition	Duration	Qual Device: TPS79601DCQRM3	Qual Device: TPS79501DCQRM3	Process QBS Reference: TLV62568DBVR	Package QBS Reference: TPS73701QDCQRM3Q1	Package QBS Reference: TPS73733DCQRM3
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	-
FTY	E6	Final Test Yield	-	-	1/All/0	1/All/0	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device [TPS79601DCQRM3](#) is qualified at MSL2 260C
- Qual Device [TPS79501DCQRM3](#) is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2503-072

For alternate parts with similar or improved performance, please visit the product page on TI.com

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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